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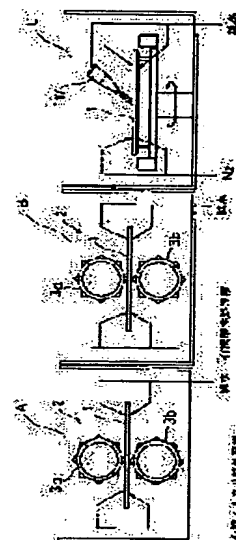
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(54) SUBSTRATE TREATMENT METHOD

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a substrate treatment method which can prevent metal impurity ions from attaching, without corroding metallic wirings, etc., in a substrate surface, and can improve the cleanliness level of a substrate by surely removing particle and metal impurities which attach to a recess and a step part generated in a metal wiring.

SOLUTION: A substrate 1 is treated in a first process A for cleaning with organic alkaline treatment liquid, a second process B for cleaning after the first process by means of organic acid treatment liquid and a third process C for cleaning, after the second process by means of ultrasound cleaning fluid oscillated by ultrasonic wave. An organic alkaline treatment liquid and organic acid treatment liquid are non-reactive to a metallic material of a metal wiring of the substrate 1 and can improve the cleanliness level of the substrate 1, by preventing metal impurity ions from attaching, without corroding the metal wirings, etc., of a substrate surface; since it contains complexing agent which forms a complex with particles in a metallic material and metals included in polishing solution, when the substrate 1 is chemomechanically polished.



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